GSDSS1 A1F Series

Schottky Barrier Diode

Product Description

Reverse Voltage 40V to 100V. Forward Current 1.0A

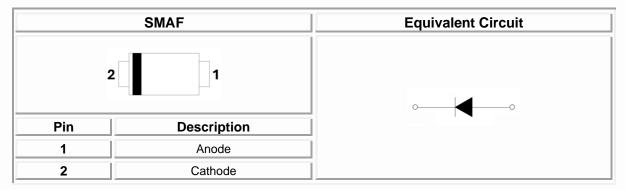
Features

- Low Forward Voltage Drop
- Low Power Loss, High Efficiency
- RoHS Compliant and Halogen Free

Mechanical Data

- Case: Molded Plastic, SMAF Package
 Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Color Band denotes Cathode End

Package and Pin Assignment



Ordering and Marking Information

Ordering Information				
Part Number	Package	Marking Code	Quantity/Reel	
GSDSS14A1F	SMAF	SS14F	3000 PCS	
GSDSS16A1F	SMAF	SS16F	3000 PCS	
GSDSS110A1F	SMAF	SS110F	3000 PCS	

GSDSS1 1 1 A1 F

- **Product Code:**GSDSS1
- Voltage Code:
 - 1 1 is 4, 6, and 10.
 - For examples 4 stands for 40V and 10 stands for 100V
- Package Code:

A1 for SMAF Package

- Green Level:
 - F for RoHS Compliant and

Halogen Free



Marking Information

SS1 11 F

- Product Code:

SS1

- Voltage Code:

1 1 is 4, 6, and 10.

For examples 4 stands for 40V

and 10 stands for 100V

- Green Level:

F for RoHS Compliant and

Halogen Free

Electrical Characteristics

(Ratings at 25° C ambient temperature unless otherwise specified. Single phase, half wave, 60HZ, resistive or inductive load. For capacitive load, derate current by 20%.)

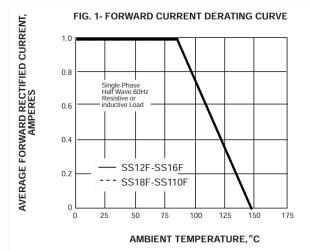
Symbol	Description	14A1F	16A1F	110A1F	Unit
V _{RRM}	Maximum Repetitive Peak Reverse Voltage	40	60	100	V
V _{RMS}	Maximum RMS Voltage	28	42	70	V
V _{DC}	Maximum DC Blocking Voltage	40	60	100	V
I _(AV)	Maximum Average Forward Rectified Current	1.0			А
IFSM	Peak Forward Surge Current, 8.3ms Single Half-Sine-Wave Superimposed on rated Load (JEDEC Method)	30		A	
VF	Maximum Forward Voltage at 1.0A	0.55	0.70	0.85	v
I _R	Maximum Reverse Current at Rated DC Blocking Voltage T _A =25°C		0.5		mA
	T _A =100°C	6.0	5.0		mA
CJ	Typical Junction Capacitance ⁽¹⁾	110	90		pF
Reja	Typical Thermal Resistance ¹	88			°C/W
TJ	Junction Temperature Range	-65 to 150			°C
Тѕтс	Storage Temperature Range	-65 to 150		°C	

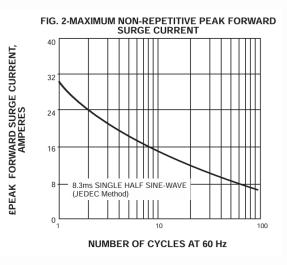
NOTES:

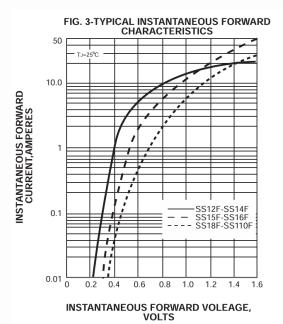
- 1. Measured at 1MHz and applied reverse voltage of 4.0 V_{DC}.
- 2. Mounted with 0.2 x 0.2" (5.0 x 5.0mm) Copper Pad Areas

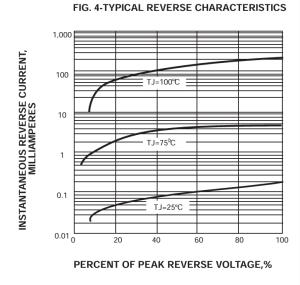


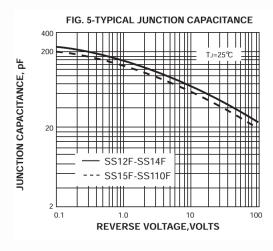
Typical Characteristics (Ratings at 25°C Ambient Temperature Unless Otherwise Specified.)

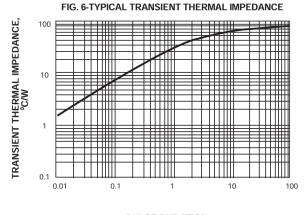










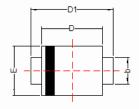


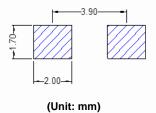
 $t, \hbox{\tt PULSE DURATION}, \hbox{\tt sec}.$

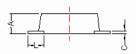
SMAF

Package Dimension

Recommended Land Pattern









Dimensions				
SYMBOL	Millimeters		Inches	
	MIN	MAX	MIN	MAX
Α	0.90	1.30	0.035	0.051
b	1.20	1.60	0.047	0.063
D	3.25	3.75	0.128	0.147
D1	4.30	4.90	0.169	0.193
E	2.30	2.70	0.091	0.106
С	0.05	0.3	0.002	0.012
L	1.20	MAX	0.047	7 MAX

NOTE:

Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.



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